Materials Declaration

Package	TQFP_EP
Body Size	7 x 7 x 1.0 (5.1 mm exposed pad)
LeadCount	48
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.91	7.61 E-02	524680
Resin	12.78	1.12 E-02	77153
Carbon black	0.31	2.72 E-04	1875
Subtotal		8.76 E-02	603708

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	3.22 E-02	221803
Ni	3.00	1.00 E-03	6914
Si	0.65	2.17 E-04	1496
Mg	0.15	5.00 E-05	345
Subtotal		3.34 E-02	230557

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	3.31 E-04	2282

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	5.26 E-03	36230

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.10 E-03	7610

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	1.47 E-02	101589

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	72.4	1.89 E-03	13048
Epoxy compound	18.1	4.73 E-04	3260
Anhydrides	6.8	1.78 E-04	1227
Polymeric material	2.7	7.10 E-05	489
Subtotal		2.62 E-03	18025

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES
Cd	None Detected	EPA Method 3051A/3052. ICP-OES
Hg	None Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	None Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	None Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	None Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES
Cd	None Detected	EPA Method 3051A/3052. ICP-OES
Hg	None Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	None Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	None Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	None Detected	EPA Method 3540C/3550C. GC/MS.

Package Totals

Weight (g)	PPM
1.45 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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